

ABSTRACT

In a semiconductor device provided with a thinned semiconductor element, the present invention intends to inhibit damage of the semiconductor element in the neighborhood of its outer periphery so as to improve reliability. A plurality of external connection terminals are formed on a front surface of the thinned semiconductor element. A plate higher in rigidity than the semiconductor element is adhered with a resin binder to a rear surface of the semiconductor element. An outer shape of the plate is made larger than that of the semiconductor element, and the resin binder covers a side face of the semiconductor element to form a reinforcement portion for reinforcing a periphery of the semiconductor element.

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